S/N: 09/996,430 Atty Dkt No. VEI 0374 PUS

Amendments to the Specification:

Please amend the paragraph beginning on page 8, at line 22 as shown below:

Alternatively, instead of the stakes 22, the infrared-absorbing material may take the form of a heat-activated adhesive typically applied in liquid form to one or both of the inner surfaces 26 and 28 of the front panel 16 and the back plate 18, respectively, about the switch pocket in which the switch 20 is positioned. The infrared radiation from the lamps 38 travels or propagates through the back plate 18 and is absorbed by the adhesive for a time sufficient to heat the adhesive to a desired temperature at which the adhesive is activated. The adhesive, when cooled, fixedly secures the back plate 18 to the front panel 16. In this way, a much cheaper adhesive than what is conventionally used may be employed to secure or bond the plastic parts together. Details of this alternative method and system are found in the abovenoted application entitled "Method And System For Bonding Plastic Parts Together" now issued as U.S. Patent No. 6,251,202, which is hereby incorporated by reference in its entirety.